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(71) **Applicant** *(for all designated States except US)*: **LAM RESEARCH CORPORATION** [—/US]; 4650 Cushing Parkway, Fremont, California CA-94538 (US).

(71) **Applicant** *(for BZ only)*: **LAM RESEARCH AG** [—/AT]; SEZ-Strasse 1, A-9500 Villach (AT).

(72) **Inventors; and**

(75) **Inventors/Applicants** *(for US only)*: **KOLICS, Artur** [HU/US]; 785 Praderia Circle, Fremont, California 94539 (US). **LEE, Willliam, T.** [US/US]; 3604 Oakhurst Court, Dublin, California 94539 (US). **REDEKER, Fritz** [US/US]; 1801 Sioux Drive, Fremont, California 94539 (US).

(74) **Agent**: **KONTRUS, Gerhard**; SEZ-Strasse 1, A-9500 Villach (AT).

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(54) **Title**: METHODS, DEVICES, AND MATERIALS FOR METALLIZATION

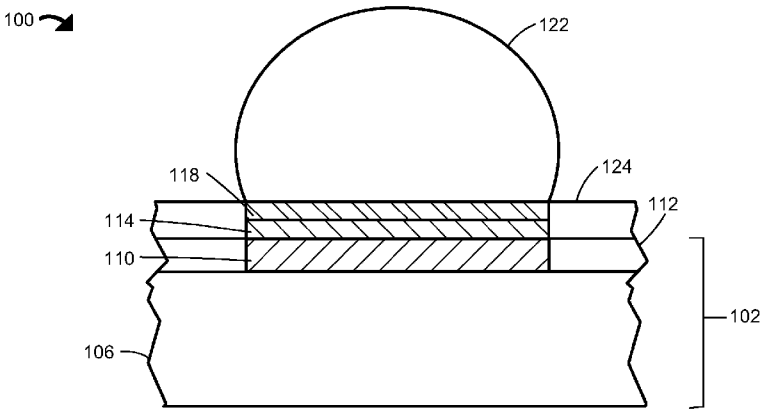


FIG. 2

(57) **Abstract**: A method of making an electronic device which in one embodiment comprises providing a substrate, electrolessly depositing a barrier metal at least on portions of the substrate, and using wet chemistry such as electroless deposition to deposit a substantially gold-free wetting layer having solder wettability onto the barrier metal. An electronic device which in one embodiment comprises a metallization stack. The metallization stack comprises a barrier metal deposited electrolessly and a substantially gold-free wetting layer deposited on the barrier metal, and the wetting layer is wettable by solder.

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